

Full Material Declaration for attached parts list

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Diotec Semiconductor AG

DUNS-Nummer: 330866844

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Declarations Autorisiert durch:

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Materialien und Stoffe

Verwendung/Andordnung	Material group	% w/w des Materials im Artikel	Substances in the material	CAS Number	% w/w des Stoffs im Artikel
Chip (die)	Other inorganic materials	4.00000%	Silicon nitride (Si ₃ N ₄)	12033-89-5	0.51000%
			Quartz (SiO ₂)	14808-60-7	0.55000%
			ALUMINIUM	7429-90-5	1.03000%
			Gold	7440-57-5	4.24000%
			Silicon	7440-21-3	93.67000%
Die attach	Other special metals	3.60000%	2-Ethylhexyl glycidyl ether	2461-15-6	8.00000%
			Phenol, polymer with formaldehyde, glycidyl ether	28064-14-4	15.00000%
			ARGENTUM	7440-22-4	77.00000%
Encapsulation	EP (Epoxy resin)	43.10000%	Carbon black	1333-86-4	0.20000%
			Cristobalite	14464-46-1	0.50000%
			ANTIMONY TRIOXIDE	1309-64-4	2.00000%
			TBBA-epichlorhydrin oligomer	40039-93-8	2.00000%
			Phenol, polymer with formaldehyde	9003-35-4	10.00000%
			Formaldehyde, polymer with (chloromethyl)oxirane and 2- methylphenol	29690-82-2	13.00000%
Inner preparation	Gold	0.10000%	Quartz sand	60676-86-0	72.30000%
			Gold	7440-57-5	100.00000%
Leadfinish	Tin plating	0.10000%	Tin	7440-31-5	100.00000%

Leadframe	Highly alloyed cast iron	49.10000%	Copper	7440-50-8	0.12000%
			ARGENTUM	7440-22-4	1.40000%
			Nickel	7440-02-0	40.98000%
			Iron	7439-89-6	57.50000%

Beigefügte Artikelliste

Part number	Artikelbezeichnung	Artikelmasse	Artikelmasse UoM
SOT-363	SOT-363	0.01	g